Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

Name / Model #1 HP Pavilion dv7-1200 to dv7-1399 Series Notebook
Name / Model #2
Name / Model #3
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother board, Touch pad, TV card</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Battery, RTC Battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Power cord</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>Type-cross #1 (JIS B 4633-1987)</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

## 3.0 Product Disassembly Process

### 3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Get out cell battery.
2. Loose four M2.5xL4 screws on Main HDD door then take out Main HDD
3. Loose one M2xL3 screw than take out mini card from Main HDD door housing
4. Loose three M2.5xL4 screws on 2\textsuperscript{nd} HDD door then take out 2\textsuperscript{nd} HDD
5. Loose one M2xL3 screw than take out TV tuner board
6. Loose three M2.5xL6.5 screws in HDD housing and Loose three M2.5xL4 screws In battery housing region and two M2.5xL6.5 screws on both side of Battery housing.
7. Reverse chassis and take out kb retainer
8. Loose four M2xL3 and take out keyboard
9. Take out Main speaker
10. Loose four M2xL6.5 and take out lcd module
11. Loose four M2xL3 in Top bracket and two M2.5xL6.5 on Battery connector upper side.
12. Loose four M2xL4 screws from hinge cavity on rear side
13. Reverse Chassis and loose one M2.5xL6.5 screw near on TV card then take out ODD
14. Loose eleven M2.5xL6.5 screws on base
15. Loose three M2.5xL4 (Big head) screws on 2\textsuperscript{nd} HDD housing
16. Reverse chassis and take out top_assy
17. Loose three M2.5xL4 screw then takeout MB and ODD board
18. Loose four spring screws from CPU region and three normal screw from VGA region then take out thermal module from MB.
19. Loose a M2.5xL4 screw then take out audio board from BASE case assy.
20. Loose a M2.5xL4 screw then take out USB board from BASE case assy.
21. Loose a M2.5xL6.5 screw then take out DC-IN bracket from BASE case assy.
22. Loose a M2.5xL1.8 screw then take out Finger printer module from top_assy
23. Loose a M2xL3 screw then take out bluetooth from top_assy
24. Loose two M2.5xL5 screws, then take out LCD bezel
25. Loose eight M2.5xL5 screws then take out hinge and Loose four M2xL3 screws then take out LCD module.

### 3.2 Optional Graphic
If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
# Standard Operating Procedure

<table>
<thead>
<tr>
<th>MODEL</th>
<th>LP173WD1-TLC1</th>
<th>LP173WD1-TLD1</th>
</tr>
</thead>
<tbody>
<tr>
<td>Purpose</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Issued date</td>
<td>2008.10.27</td>
<td></td>
</tr>
<tr>
<td>Dep.</td>
<td></td>
<td>NB Qualification Team</td>
</tr>
</tbody>
</table>

**LCM Disassembly Method**

<table>
<thead>
<tr>
<th>Prepared by</th>
<th>Checked by</th>
</tr>
</thead>
<tbody>
<tr>
<td>Sumi Chae</td>
<td>Rich Kim</td>
</tr>
</tbody>
</table>

## STEP 1
**Remove Side Tape & Bottom Tape**

- **Side Tape**
- **Bottom Tape**

## STEP 2
**Remove PCB Cover Shield**
**STEP 3** Separate FPC from PCB

**STEP 4** Separate Metal Chassis from Plastic Frame (From Bottom Hook to Left/Right Hook)
STEP 5  Separate Panel Assembly from Backlight Unit